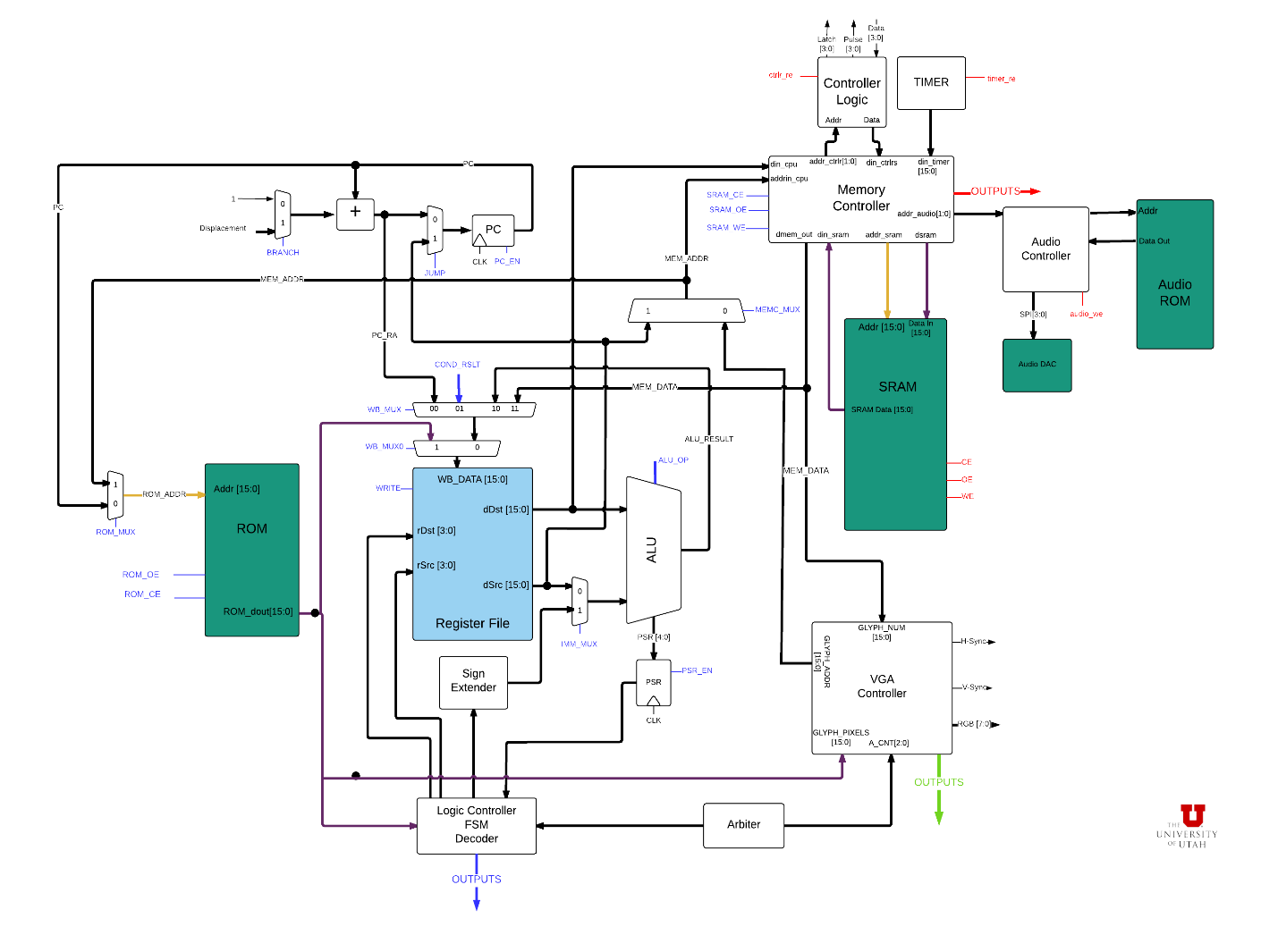
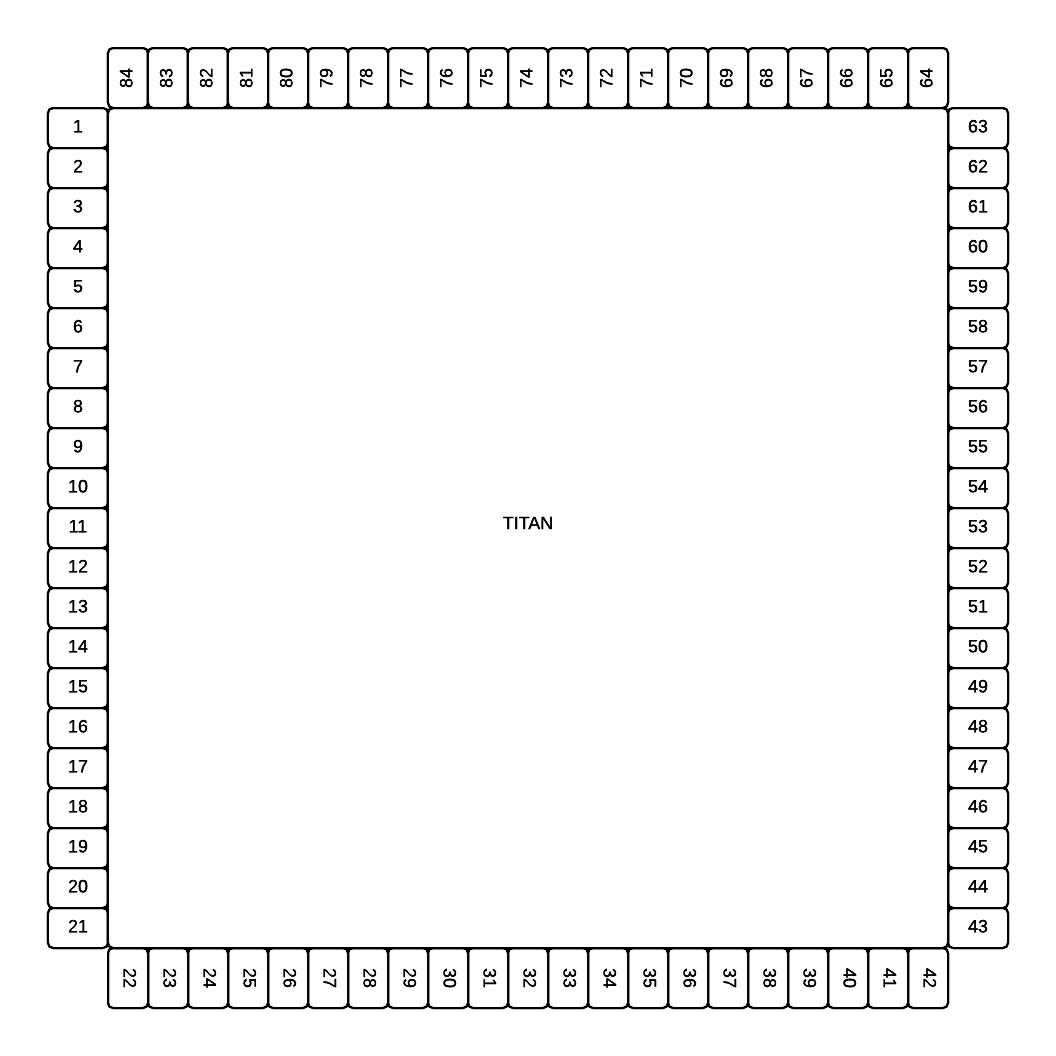
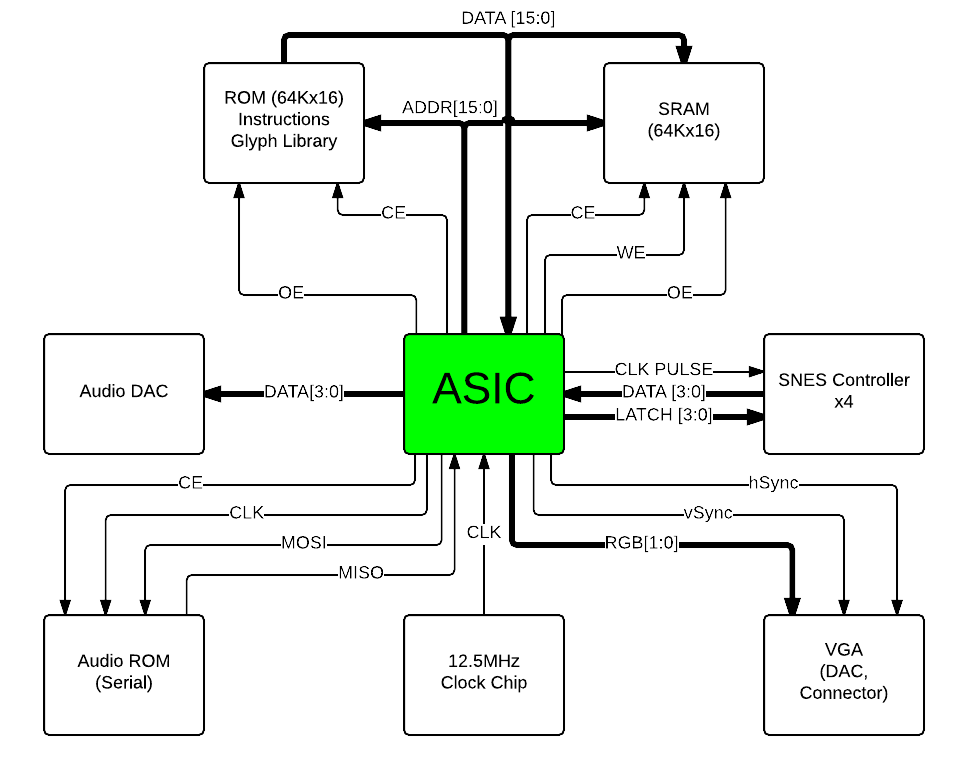
**T.E.S.S. Data Sheet**

1. **Overview**
   1. **Located in the proposal**
   2. **Talk about general overview of the chip**
2. **Features**
   1. **Mention VGA, AUDIO, external memory interface from a high level**
3. **Abbreviations**
   1. **Tabulate possible abbreviations that might be used in the paper**
4. **Block Diagram  
   **
5. **Pin Layout  
   **
6. **Pin Table**

|  |  |  |
| --- | --- | --- |
| Name | Number | Description |
|  | 1 |  |
|  | 2 |  |
|  | 3 |  |
|  | 4 |  |
|  | 5 |  |
|  | 6 |  |
|  | 7 |  |
|  | 8 |  |
|  | 9 |  |
|  | 10 |  |
|  | 11 |  |
|  | 12 |  |
|  | 13 |  |
|  | 14 |  |
|  | 15 |  |
|  | 16 |  |
|  | 17 |  |
|  | 18 |  |
|  | 19 |  |
|  | 20 |  |
|  | 21 |  |
|  | 22 |  |
|  | 23 |  |
|  | 24 |  |
|  | 25 |  |
|  | 26 |  |
|  | 27 |  |
|  | 28 |  |
|  | 29 |  |
|  | 30 |  |
|  | 31 |  |
|  | 32 |  |
|  | 33 |  |
|  | 34 |  |
|  | 35 |  |
|  | 36 |  |
|  | 37 |  |
|  | 38 |  |
|  | 39 |  |
|  | 40 |  |
|  | 41 |  |
|  | 42 |  |
|  | 43 |  |
|  | 44 |  |
|  | 45 |  |
|  | 46 |  |
|  | 47 |  |
|  | 48 |  |
|  | 49 |  |
|  | 50 |  |
|  | 51 |  |
|  | 52 |  |
|  | 53 |  |
|  | 54 |  |
|  | 55 |  |
|  | 56 |  |
|  | 57 |  |
|  | 58 |  |
|  | 59 |  |
|  | 60 |  |
|  | 61 |  |
|  | 62 |  |
|  | 63 |  |
|  | 64 |  |
|  | 65 |  |
|  | 66 |  |
|  | 67 |  |
|  | 68 |  |
|  | 69 |  |
|  | 70 |  |
|  | 71 |  |
|  | 72 |  |
|  | 73 |  |
|  | 74 |  |
|  | 75 |  |
|  | 76 |  |
|  | 77 |  |
|  | 78 |  |
|  | 79 |  |
|  | 80 |  |
|  | 81 |  |
|  | 82 |  |
|  | 83 |  |
|  | 84 |  |

1. **Data path**
   1. **Core**
   2. **Audio**
   3. **VGA**
   4. **Memory Map**
2. **Peripheral interface**
3. **Electrical Characteristics**
4. **Application   
   **
5. **Package Dimensions   
   Available through MOSIS**